



## [WeD1] Lithography Process

<b>Session Date</b>	November 12 (Wed.), 2025
<b>Session Time</b>	09:00-10:40
<b>Session Room</b>	Room D (Sydney Room, 2F)
<b>Session Chair</b>	Dr. Jeong-Ho Yeo (Applied Materials, Korea)

### [WeD1-1] [Invited]

09:00-09:30

#### **Journey to the Future: Low & High NA EUV Lithography for Next Generation Logic Devices**

Jong-Hwa Baek (Samsung Electronics Co., Ltd., Korea)

### [WeD1-2] [Invited]

09:30-10:00

#### **EUV Mask Technology: Evolution and Future Outlook**

Chan-Uk Jeon (Tekscend Photomask Corp., Japan)

### [WeD1-3] [Invited]

10:00-10:20

#### **SEM Overlay Target Optimization for NZO Improvement by Measuring Device Like Target Using E-Beam Simulation**

You Jin Kim, Jeong Ho Yeo, Youngje Um (Applied Materials Korea, Korea), Jenny Perry, Noam Oved, Uri Smolyan, Tal Itzkovich, Michael Shifrin (Applied Materials Israel, Israel), Young Jin Cha, Baek Jun Kim (Applied Materials Korea, Korea), Ikjun Jang, Il Hwan Kim, Byoungsoon Kim, Sungbin Jeon, Muyeong Lee, Hyunju Song, Myeongcheol Go, Narim Noh, Hachul Shin, Sangsu Jeong, Eunho Choi, Jinhong Park, and Changmin Park (Samsung Electronics Co., Ltd., Korea)

### [WeD1-4] [Invited]

10:20-10:40

#### **Development of EUV Pellicles Supporting High EUV Power**

Prashant Purwar, Dongyeong Yoo, Munsu Choi, Arim Kim, Chulkyun Park, Sangmin Jeong, Byoung Hoon Seung, and Juhee Hong (S&S TECH., Korea)